MLCC - NPO (COG)

NPO/COG for General-use is class I high frequency capacitor, its capacitance is very stable, almost will not change along with the temperature, voltage and time. Specially be suitable for high frequency circuits.

FEATURES

- Miniature size
- Wide capacitance, TC, voltage and tolerance range
- Industry standard sizes
- Available for wave, reflow or vapor phase solder

HOW TO ORDER

0805		CG	CG 102			J	500			N	т	
I	I		I I		I		I		I		I	
Α	В		B C		D		E		F		G	
Size Code	Size Code Dielectric		Capad	citance(pF)	Т	olerance	Rated Voltage Terminatio		ermination	Packaging Style		
0402	00	COG	1R0	1pF	В	±0.10pF	160	16V	S	Silver	No Mark	Bulk
0603	CG	(NPO)	100	10pF	С	±0.25pF	250	250V	N	Nickel Barrier	Т	Tape & Reel
0805			101	100pF	D	±0.5pF	500	50V	IN	Tin Plating	В	Bulk Package
1206			102	1000pF	F	±1.0%	630	63V				
			103	10000pF	G	±2.0%	101	100V				
					J	±5.0%	201	200V				
					К	±10%	501	500V				
					Μ	±20%	102	1000V				
							202	2000V				

TERMINATION DIAGRAMS



NOTE: Other Termination Available Upon Request (Contact Factory)

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SIZE CODE CAPACITANCE and VOLTAGE

	Туре		Dimensio	Voltage	Capacitance(pF)		
Size Code	Metric Expression	L	w	т	WB		NPO(COG)
			0.50±0.05	0.50±0.05		10V	0R5~471
0402	1005	1.00+0.05			0.25+0.1	16V	0R5~471
0402	1005	1.00±0.05			0.25±0.1	25V	1R0~471
						50V	1R0~221
						25V	0R5~102
0603	1608	1 60+0 1	0 80+0 10	0 80+0 1	0 20+0 1	50V	0R5~102
0005	1000	1.0010.1	0.0010.10	0.0010.1	0.3010.1	100V	0R5~561
						200V	0R5~331
				0.80±0.10 1.00±0.10		25V	0R5~472
			1.25±0.20		0.5±0.25	50V	0R5~472
0805	2012	2.00±0.20				100V	0R5~102
						200V	0R5~821
				1.25±0.20		500V	0R5~471
					0.50±0.25	25V	0R5~153
		3.20±0.30	1.60±0.20	0.80±0.10 1.00±0.10		50V	0R5~153
						100V	0R5~152
1206	3216					200V	0R5~102
						500V	0R5~821
				1.25±0.20		1000V	0R5~471
						2000V	0R5~682
						25V	561~153
						50V	561~153
				1.25±0.30		100V	561~472
1210	3225	3.20±0.30	2.50±0.30		0.75±0.25	200V	101~472
				1.25±0.30		500V	101~222
						1000V	101~102
						2000V	101~561

PACKAGING

Structure and Dimension

Tape & Reel						
Α	В	С	D	Е	F	G
178±2.00	3.00	13±0.50	21±0.80	50 min	10.0±1.50	12 max
330±2.00	3.00	13±0.50	21±0.80	50 min	10.0±1.50	12 max



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Paper Tape в Size Α 0402 0.6±0.2 1.1±0.2 0603 1.1±0.2 1.4±0.2 0805 1.45±0.2 2.3±0.2 1206 1.8±0.2 3.4±0.2 Embossed Tape Size Α В 0402 0.5±0.2 1.2±0.2 0603 0.8±0.2 2.0±0.2 0805 1.65±0.2 2.4±0.2 1206 2.0±0.2 3.6±0.2



Cartridge						
Symbol	Α	В	D	С	т	E
Dimension	6.8±0.1	8.8±0.1	12±0.1	15±0.1-0	2±0-0.1	4.7±0.1
Symbol	F	w	G	н	L	I
Dimension	31.5±0.2-0	36±0-0.2	19±0.35	7±0.35	110±0.7	5±0.35



Packaging Quantity

Sino	Quantity							
JIZE	Paper Tape Taping	Embossed Taping	Normal Bulk					
0402	10000		10000					
0603	4000		4000					
0805	4000	2000 / 3000	4000					
1206	4000	2000 / 3000	4000					
1210		2000 / 3000						
1812		1000						
2225								
3035								

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NPO(COG) DIELECTRIC CHARACTERISTIC INDUCTION & TEST METHOD

ltem		Specification			Test Method			
Operating		epoonouton			rest metriou			
Temperature		-55°C ~ 125°C						
Range								
Appearance	 Good ceran The chips h smooth. No exposed The outer e damages or No outer ele is less than 	hic body color continuity ave no visual damages and must be very I inner-electrode, cracks or holes lectrode should have no cracks, holes surface oxidation ectrode prolongation or the prolongation half of that of the termination width.	Check by using microscope ≥10X					
Canacitanaa		this the energified televance	4	Magguring			0/	
Dissipation Factor (DF)	VVI	≤0.15%	 Measuring Temperature: 25°C±5°C, Humidity: 30% 75% Measuring Voltage: 1.0±0.2V Measuring Frequency: C<1000pF, 1.0±0.1MHz, C≥1000pF, 1.0±0.1KHz 					
Insulation		N 5- 40 ¹⁰ 0	Must measure at rated voltage and measure the ID within 60. Fe					
Resistance		≥5x10 [™] Ω	Must measure at rated voltage and measure the IR within 60±55					
Withstanding		2016	Must measure at 3 times rated voltage, dwell time: 60±1s, no					
Voltage		>301	 short and the changing/discharging current less than 50mA Pre-heat for 60±5min at 150+0/-10°C, then set it for 24±2hrs at room temperature Measure the capacitance at -55~125°C or -55~85°C, the capacitance change ration comparing to that of 25°C must be within the specified range. 					
Capacitance Temperature Characteristic	Must meet the ca requirements v	pacitor character temperature coefficient vithin the operating temperature range						
Solderability	Tin coverage should be 95% of the outer electrode			the capacitor into 235±5°C	into ethanol or coloph eutectic solder solution speed: 25±2.5mm	nony solution, an on for 2±0.5s. /s	d then Dipping	
	Appearance	No defects visible	 Pre-heat for 60±5min at 150+0/-10°C, then s 24±2hrs at room temperature Pre-heat the capacitor according to the chart 			°C, then set it fo the chart below	r [.] Dip	
Resistance to	Capacitance Change Ratio ≤±2.5% or ±0.25pF (whichever larger)			the capacitor into $260\pm5^{\circ}$ C eutectic solder solution for $10\pm$ 1s. Then set it for 24 ± 2 hrs at room temperature, then measure.				
Soldering	D.F.	Max 0.15%	Dipping speed: 25±2.5mm/s					
				Stage	Temperature	Timer		
	I.R.	More than $50000M\Omega$		1	100°C ~ 120°C	1 min.		
				2	170°C ~ 200°C	1 min.		

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ltem		Specification	Test method				
Adhesive Strength of Termination	No removal of the	terminations or other defect shall occur	Capacitors mounted on a substrate, a force of 5N applied perpendicular to the plane of the substrate and parallel to the line joining the center of the terminations for 10±1s				
	Appearance	No defects or abnormities	Solder the capacitor to the test jig (glass epoxy resin board). The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz, shall be traversed in approximately 1min. This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (a total of 6 hours).				
Vibration Resistance	Capacitance	Within the specified tolerance range					
	D.F.	Max 0.15%					
Bending Resistance	No removal of t	ermination, crack or visible damage.	Capacitors mounted on a substrate. The board shall then be bent by 1mm at a rate of 1mm/sec with 10N force $\begin{array}{c} 0 \\ \hline \\ 1 \\ \hline \\ 45 \pm 2 \\ \hline \\ \\ \\ 45 \pm 2 \\ \hline \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$				
Temperature Cycle	No dai	nage or abnormities visible	 Heat the capacitor for 60±5min at 150+0/10°C, and then set it for 24 2hrs at room temperature. Perform five cycles according to the four heat treatments listed below. Set it for 24±2hrs at room temperature, then measure. Stage Temperature(°C) Time(min.) Lowest operating temperature ±3 Normal Temperature ±2 30±3 Normal temperature ±2 2~3 				
	Appearance	No defects or abnormities	Set the capacitor for 500+24/-0 hours at the condition of				
Humidity	Capacitance Change Ratio	≤±5% or ±0.5pF (whichever larger)	40±2°C and 90-95% humidity. Then remove and set it for 24±2 hours at room temperature, then measure.				
Laod	D.F.	Max 0.15%	Load: Apply rated voltage to the capacitor for 500+24/-0 hours at the condition of 40±2°C and 90-95% humidity. Remove and set it for 24±2 hours at room temperature, then measure.				
	I.R.	More than $10000M\Omega$					
l ife Test	AppearanceNo defects or abnormitiesCapacitance≤±5% or ±0.5pF (whichever larger)		 Apply two times the rated voltage to the capacitor for 1000±12 hours at the upper temperature limits, the charging current chauld be less than 50m 4. 				
Ene reat	D.F	Max 0 15%	 charging current should be less than 50mA. Remove and set it for 24±2 hours at room temperature, then measure. 				
	I.R.	More than $10000M\Omega$					